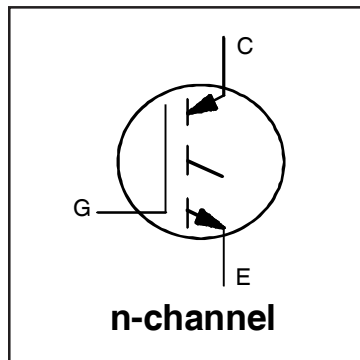


### INSULATED GATE BIPOLAR TRANSISTOR

#### Features

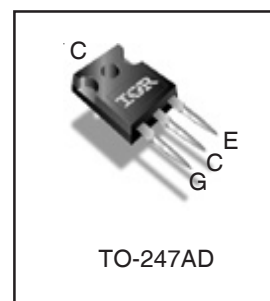
- Low  $V_{CE(ON)}$  Trench IGBT Technology
- Low switching losses
- Maximum Junction temperature 175 °C
- 5  $\mu$ S short circuit SOA
- Square RBSOA
- 100% of the parts tested for  $I_{LM}$  ①
- Positive  $V_{CE(ON)}$  Temperature co-efficient
- Tight parameter distribution
- Lead Free Package



$V_{CES} = 600V$
$I_C = 24A, T_C = 100^\circ C$
$t_{SC} \geq 5\mu s, T_{J(max)} = 175^\circ C$
$V_{CE(on)} \text{ typ.} = 1.65V$

#### Benefits

- High Efficiency in a wide range of applications
- Suitable for a wide range of switching frequencies due to Low  $V_{CE(ON)}$  and Low Switching losses
- Rugged transient Performance for increased reliability
- Excellent Current sharing in parallel operation
- Low EMI



<b>G</b>	<b>C</b>	<b>E</b>
Gate	Collector	Emitter

Base part number	Package Type	Standard Pack		Orderable part number
		Form	Quantity	
IRGP4062-EPbF	TO-247AD	Tube	25	IRGP4062-EPbF

#### Absolute Maximum Ratings

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	48	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	24	
$I_{CM}$	Pulse Collector Current, $V_{GE} = 15V$	72	
$I_{LM}$	Clamped Inductive Load Current, $V_{GE} = 20V$ ①	96	
$V_{GE}$	Continuous Gate-to-Emitter Voltage	$\pm 20$	V
	Transient Gate-to-Emitter Voltage	$\pm 30$	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	250	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	125	
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +175	°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf·in (1.1 N·m)	

#### Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Thermal Resistance Junction-to-Case	—	—	0.65	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink (flat, greased surface)	—	0.50	—	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (typical socket mount)	—	—	40	

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

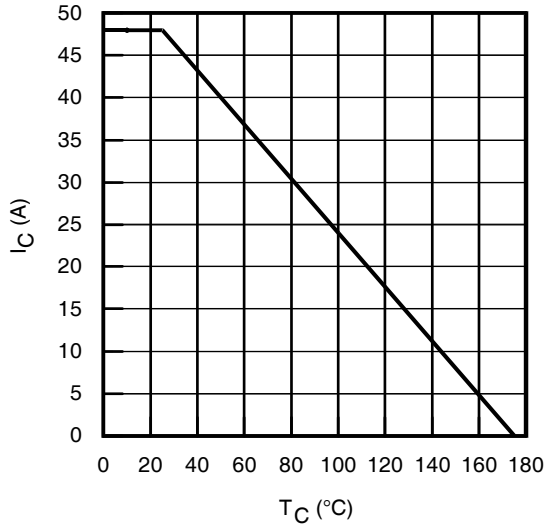
	Parameter	Min.	Typ.	Max.	Units	Conditions
V <sub>(BR)CES</sub>	Collector-to-Emitter Breakdown Voltage	600	—	—	V	V <sub>GE</sub> = 0V, I <sub>C</sub> = 100μA ②
ΔV <sub>(BR)CES</sub> /ΔT <sub>J</sub>	Temperature Coeff. of Breakdown Voltage	—	0.30	—	V/°C	V <sub>GE</sub> = 0V, I <sub>C</sub> = 1mA (25°C-175°C)
V <sub>CE(on)</sub>	Collector-to-Emitter Saturation Voltage	—	1.60	1.95	V	I <sub>C</sub> = 24A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 25°C
		—	2.03	—		I <sub>C</sub> = 24A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 150°C
		—	2.04	—		I <sub>C</sub> = 24A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 175°C
V <sub>GE(th)</sub>	Gate Threshold Voltage	4.0	—	6.5	V	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 700μA
ΔV <sub>GE(th)</sub> /ΔT <sub>J</sub>	Threshold Voltage temp. coefficient	—	-18	—	mV/°C	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1.0mA (25°C - 175°C)
g <sub>fe</sub>	Forward Transconductance	—	17	—	S	V <sub>CE</sub> = 50V, I <sub>C</sub> = 24A, PW = 80μs
I <sub>CES</sub>	Collector-to-Emitter Leakage Current	—	2.0	25	μA	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V
		—	775	—		V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V, T <sub>J</sub> = 175°C
I <sub>GES</sub>	Gate-to-Emitter Leakage Current	—	—	±100	nA	V <sub>GE</sub> = ±20V

**Switching Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

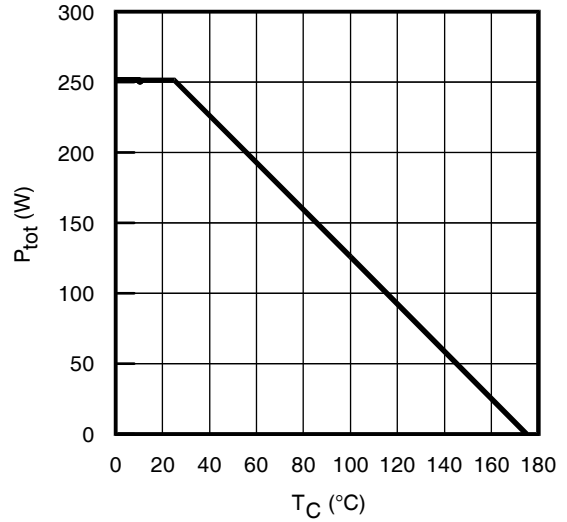
	Parameter	Min.	Typ.	Max.	Units	Conditions
Q <sub>g</sub>	Total Gate Charge (turn-on)	—	50	75	nC	I <sub>C</sub> = 24A
Q <sub>ge</sub>	Gate-to-Emitter Charge (turn-on)	—	13	20		V <sub>GE</sub> = 15V
Q <sub>gc</sub>	Gate-to-Collector Charge (turn-on)	—	21	31		V <sub>CC</sub> = 400V
E <sub>on</sub>	Turn-On Switching Loss ③	—	115	201	μJ	I <sub>C</sub> = 24A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V
E <sub>off</sub>	Turn-Off Switching Loss	—	600	700		R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH, T <sub>J</sub> = 25°C
E <sub>total</sub>	Total Switching Loss	—	715	901		Energy losses include tail & diode reverse recovery
t <sub>d(on)</sub>	Turn-On delay time	—	41	53	ns	I <sub>C</sub> = 24A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V
t <sub>r</sub>	Rise time	—	22	31		R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH, T <sub>J</sub> = 25°C
t <sub>d(off)</sub>	Turn-Off delay time	—	104	115		
t <sub>f</sub>	Fall time	—	29	41		
E <sub>on</sub>	Turn-On Switching Loss ③	—	420	—	μJ	I <sub>C</sub> = 24A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V
E <sub>off</sub>	Turn-Off Switching Loss	—	840	—		R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH, T <sub>J</sub> = 175°C
E <sub>total</sub>	Total Switching Loss	—	1260	—		Energy losses include tail & diode reverse recovery
t <sub>d(on)</sub>	Turn-On delay time	—	40	—	ns	I <sub>C</sub> = 24A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = 15V
t <sub>r</sub>	Rise time	—	24	—		R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH
t <sub>d(off)</sub>	Turn-Off delay time	—	125	—		T <sub>J</sub> = 175°C
t <sub>f</sub>	Fall time	—	39	—		
C <sub>ies</sub>	Input Capacitance	—	1490	—	pF	V <sub>GE</sub> = 0V
C <sub>oes</sub>	Output Capacitance	—	129	—		V <sub>CC</sub> = 30V
C <sub>res</sub>	Reverse Transfer Capacitance	—	45	—		f = 1.0Mhz
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				T <sub>J</sub> = 175°C, I <sub>C</sub> = 96A V <sub>CC</sub> = 480V, V <sub>p</sub> = 600V R <sub>G</sub> = 10Ω, V <sub>GE</sub> = +20V to 0V
SCSOA	Short Circuit Safe Operating Area	5	—	—	μs	V <sub>CC</sub> = 400V, V <sub>p</sub> = 600V R <sub>G</sub> = 10Ω, V <sub>GE</sub> = +15V to 0V

**Notes:**

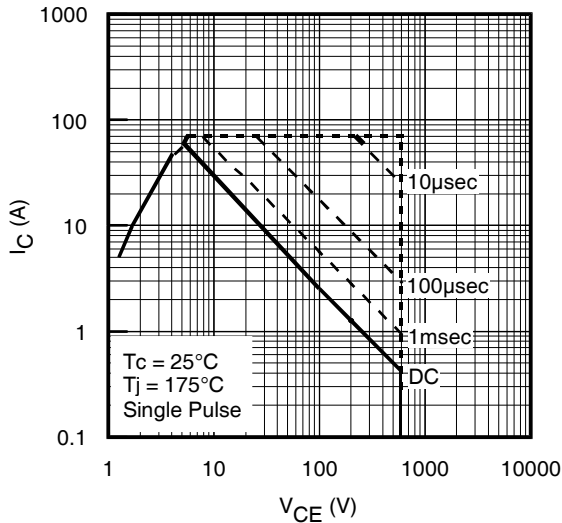
- ① V<sub>CC</sub> = 80% (V<sub>CES</sub>), V<sub>GE</sub> = 20V, L = 100μH, R<sub>G</sub> = 10Ω.
- ② Refer to AN-1086 for guidelines for measuring V<sub>(BR)CES</sub> safely.
- ③ Turn-on energy is measured using the same co-pak diode as IRGP4062DPbF.



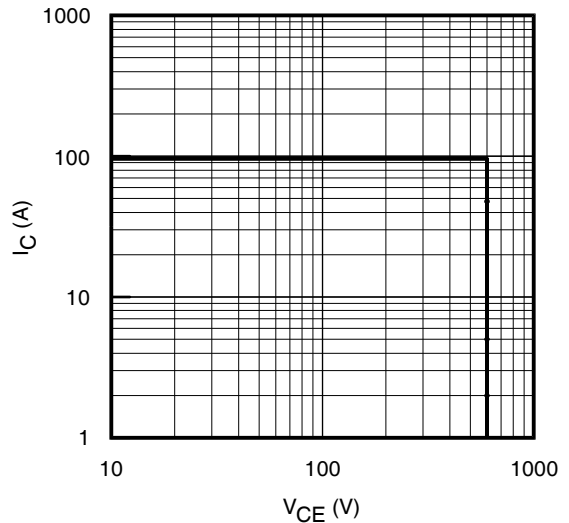
**Fig. 1 - Maximum DC Collector Current vs. Case Temperature**



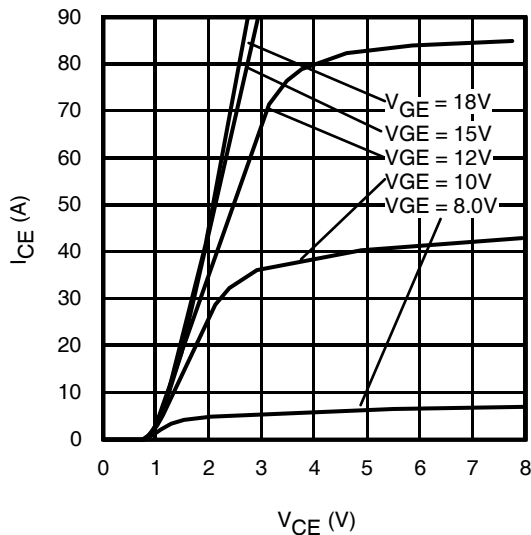
**Fig. 2 - Power Dissipation vs. Case Temperature**



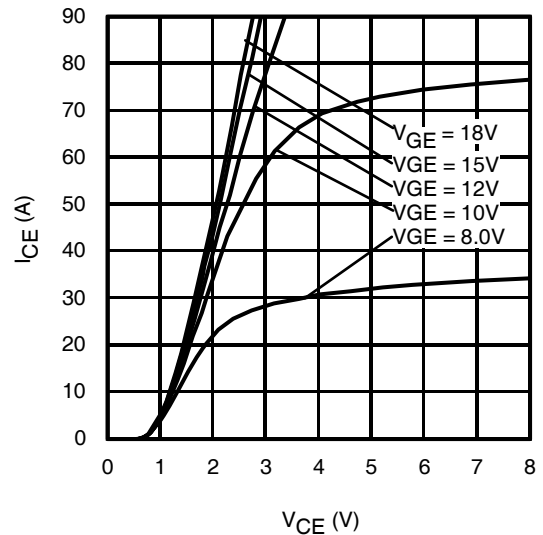
**Fig. 3 - Forward SOA**  
 $T_C = 25^\circ\text{C}$ ,  $T_J \leq 175^\circ\text{C}$ ;  $V_{GE} = 15\text{V}$



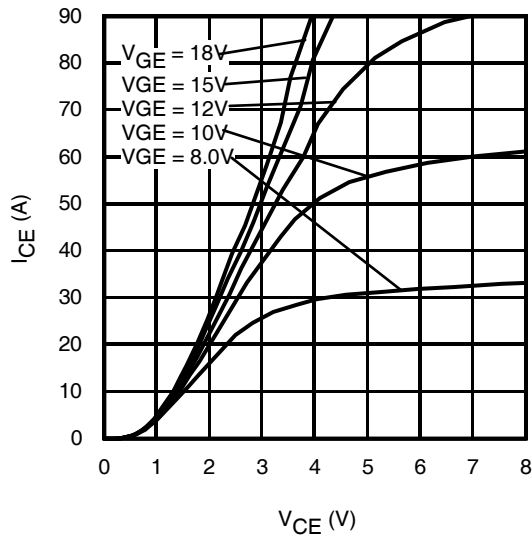
**Fig. 4 - Reverse Bias SOA**  
 $T_J = 175^\circ\text{C}$ ;  $V_{GE} = 20\text{V}$



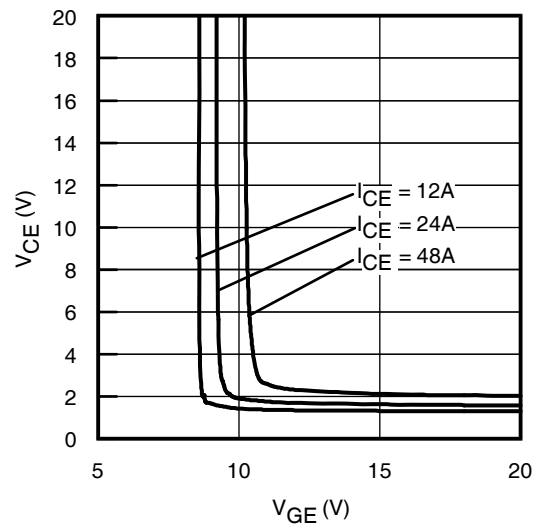
**Fig. 5 - Typ. IGBT Output Characteristics**  
 $T_J = -40^\circ\text{C}$ ;  $t_p = 80\mu\text{s}$



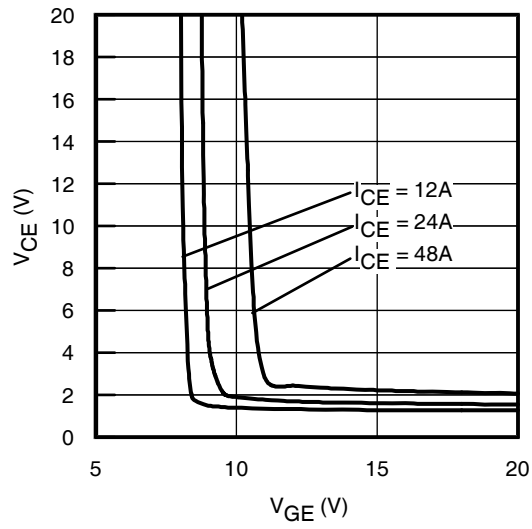
**Fig. 6 - Typ. IGBT Output Characteristics**  
 $T_J = 25^\circ\text{C}$ ;  $t_p = 80\mu\text{s}$



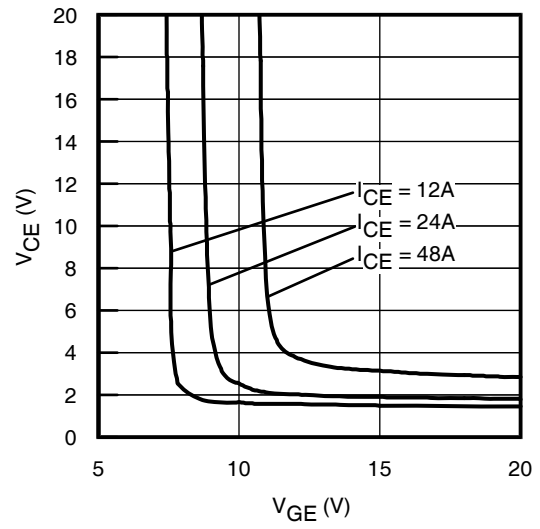
**Fig. 7 - Typ. IGBT Output Characteristics**  
 $T_J = 175^\circ\text{C}$ ;  $t_p = 80\mu\text{s}$



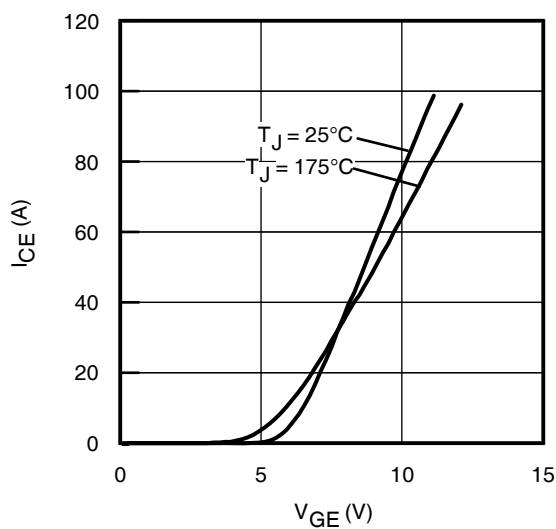
**Fig. 8 - Typical  $V_{CE}$  vs.  $V_{GE}$**   
 $T_J = -40^\circ\text{C}$



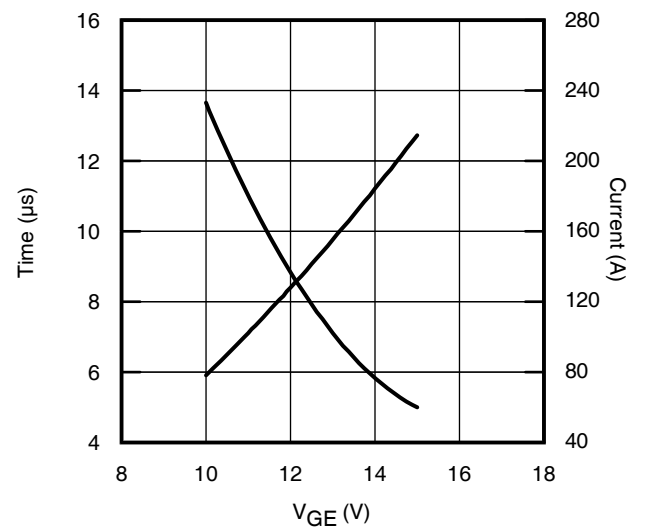
**Fig. 9 - Typical  $V_{CE}$  vs.  $V_{GE}$**   
 $T_J = 25^\circ\text{C}$



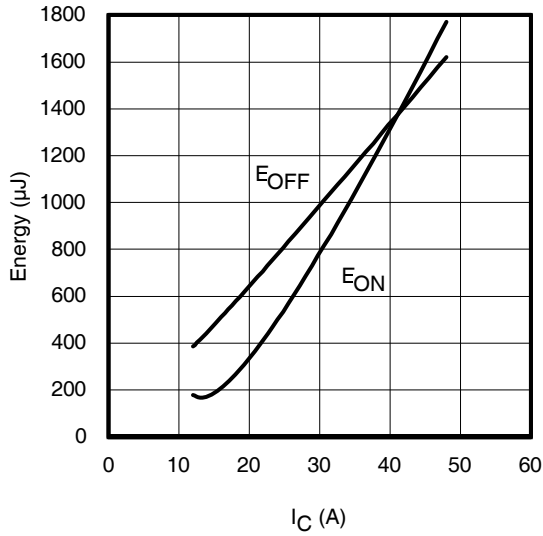
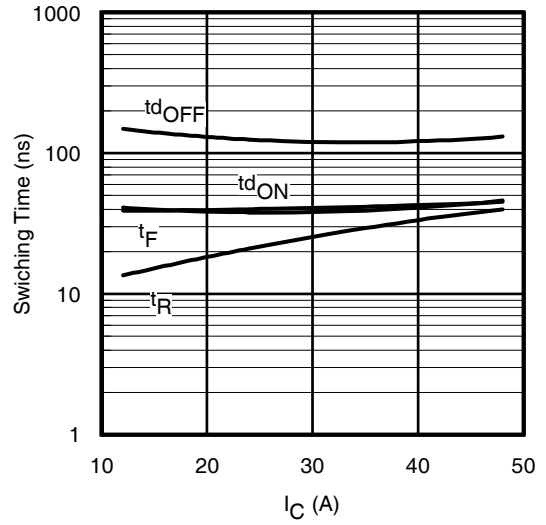
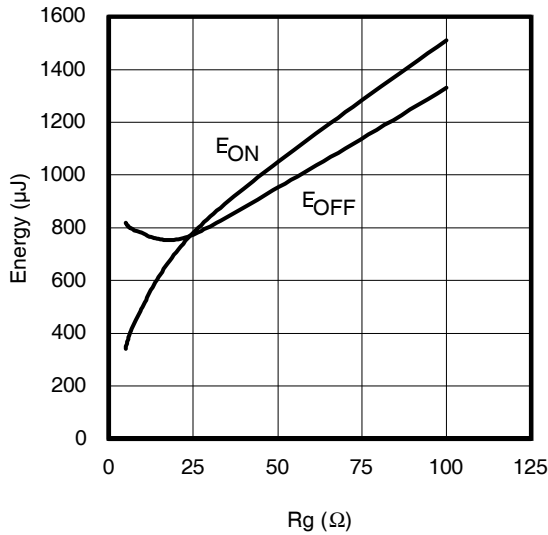
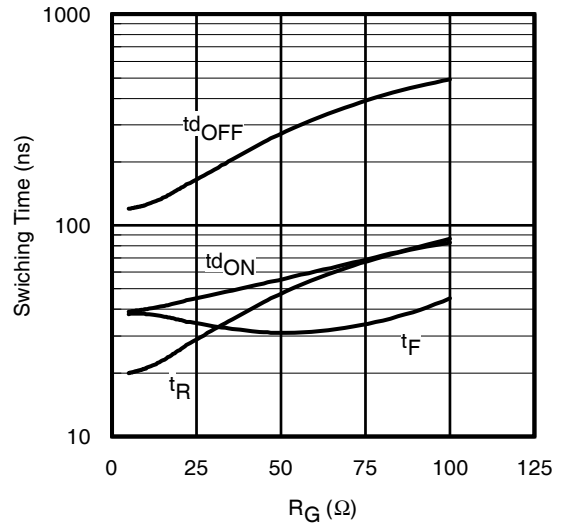
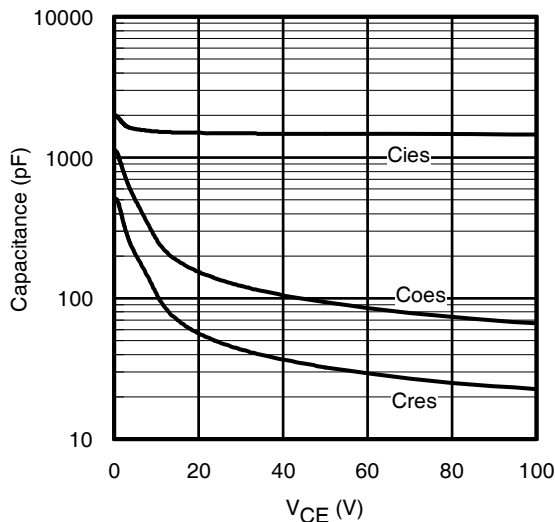
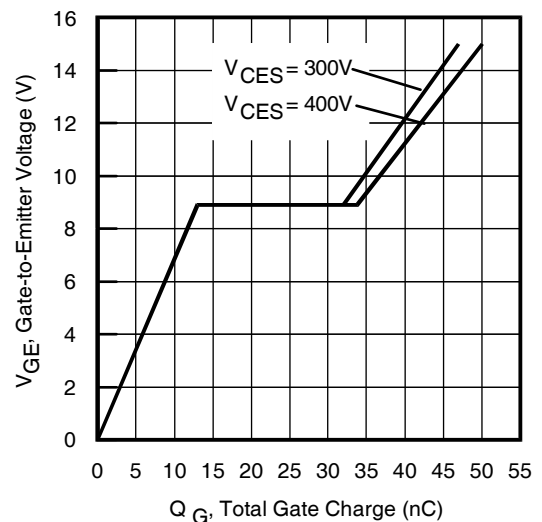
**Fig. 10 - Typical  $V_{CE}$  vs.  $V_{GE}$**   
 $T_J = 175^\circ\text{C}$

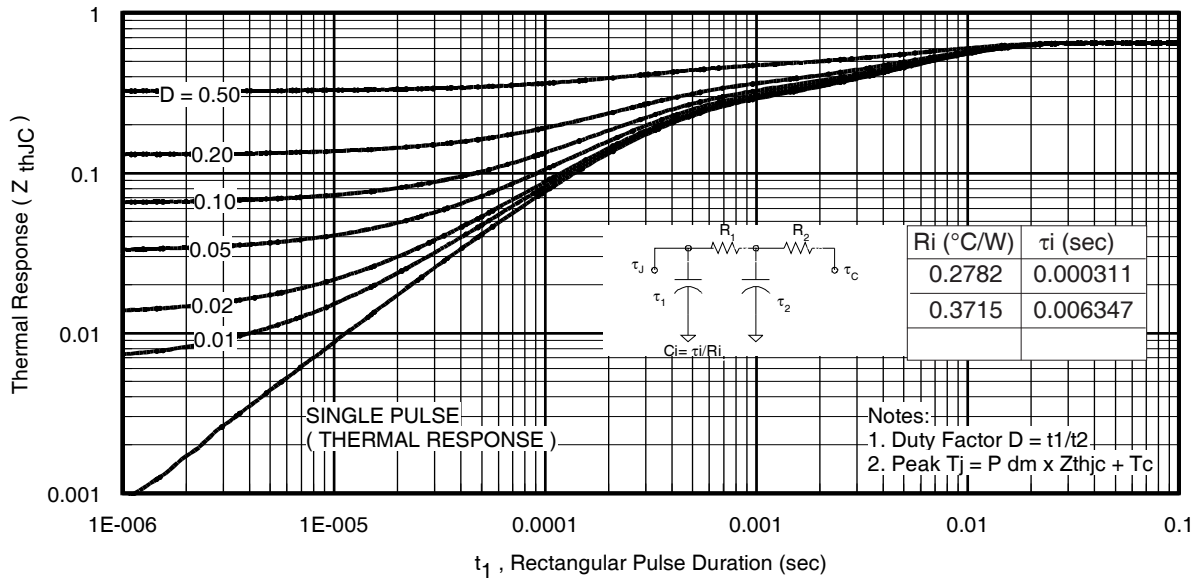


**Fig. 11 - Typ. Transfer Characteristics**  
 $V_{CE} = 50\text{V}$ ;  $t_p = 10\mu\text{s}$

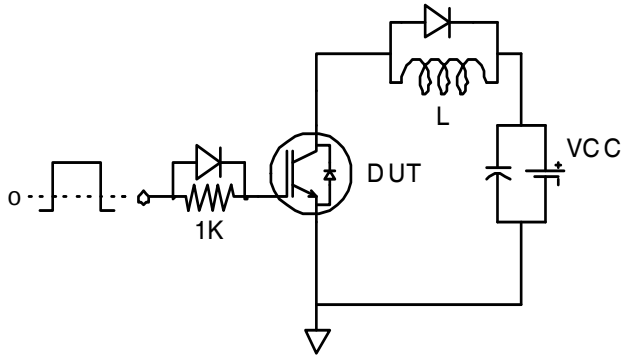
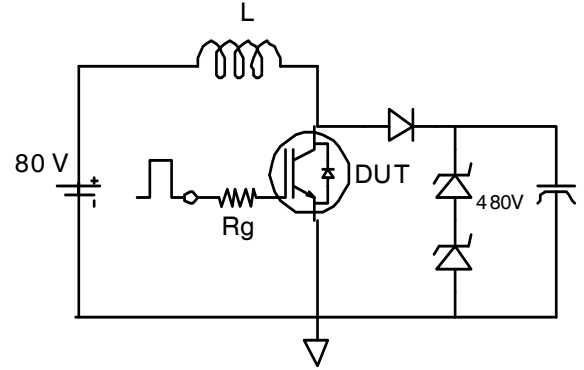
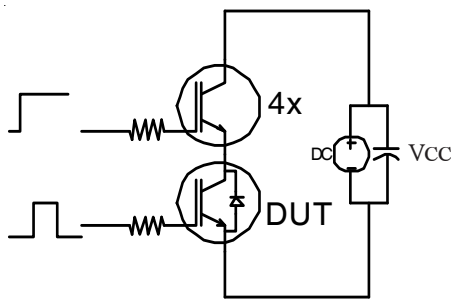
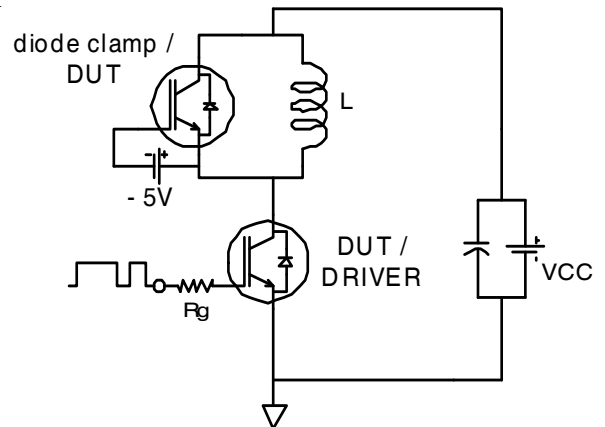
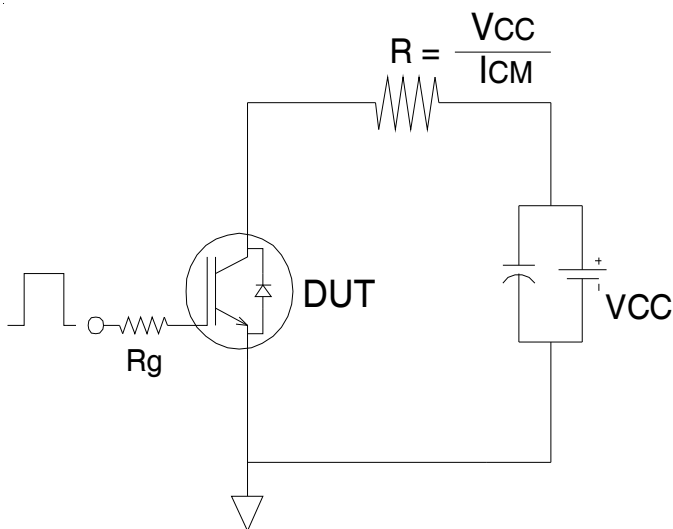
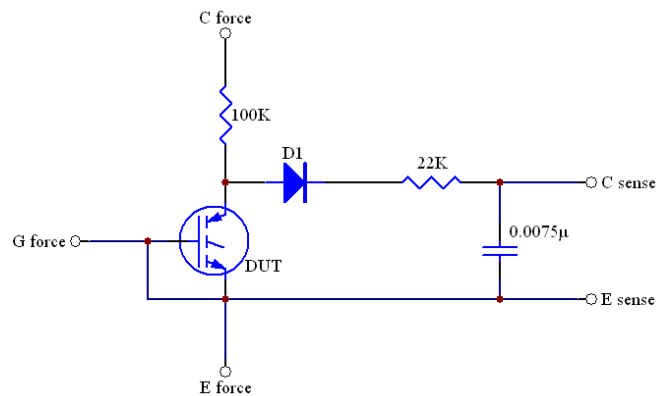


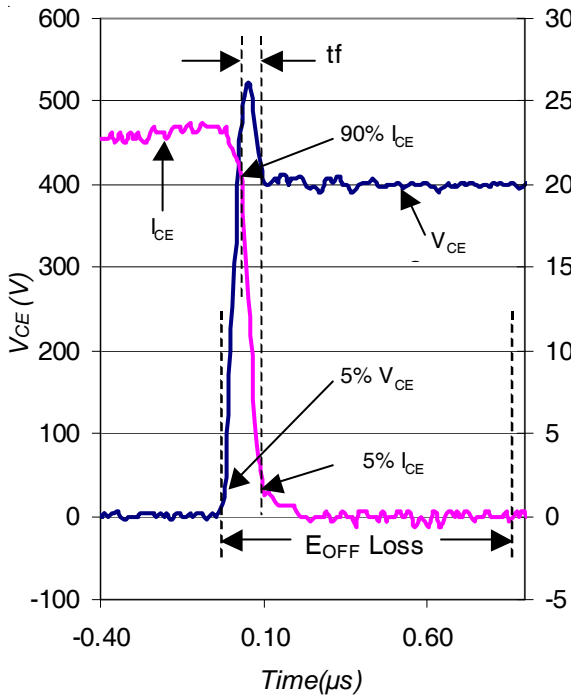
**Fig. 12 -  $V_{GE}$  vs. Short Circuit Time**  
 $V_{CC} = 400\text{V}$ ;  $T_C = 25^\circ\text{C}$


**Fig. 13 - Typ. Energy Loss vs.  $I_C$** 
 $T_J = 175^\circ\text{C}; L = 200\mu\text{H}; V_{CE} = 400\text{V}; R_G = 10\Omega; V_{GE} = 15\text{V}$ 

**Fig. 14 - Typ. Switching Time vs.  $I_C$** 
 $T_J = 175^\circ\text{C}; L = 200\mu\text{H}; V_{CE} = 400\text{V}; R_G = 10\Omega; V_{GE} = 15\text{V}$ 

**Fig. 15 - Typ. Energy Loss vs.  $R_G$** 
 $T_J = 175^\circ\text{C}; L = 200\mu\text{H}; V_{CE} = 400\text{V}; I_{CE} = 24\text{A}; V_{GE} = 15\text{V}$ 

**Fig. 16 - Typ. Switching Time vs.  $R_G$** 
 $T_J = 175^\circ\text{C}; L = 200\mu\text{H}; V_{CE} = 400\text{V}; I_{CE} = 24\text{A}; V_{GE} = 15\text{V}$ 

**Fig. 17 - Typ. Capacitance vs.  $V_{CE}$** 
 $V_{GE} = 0\text{V}; f = 1\text{MHz}$ 

**Fig. 18 - Typical Gate Charge vs.  $V_{GE}$** 
 $I_{CE} = 24\text{A}; L = 600\mu\text{H}$

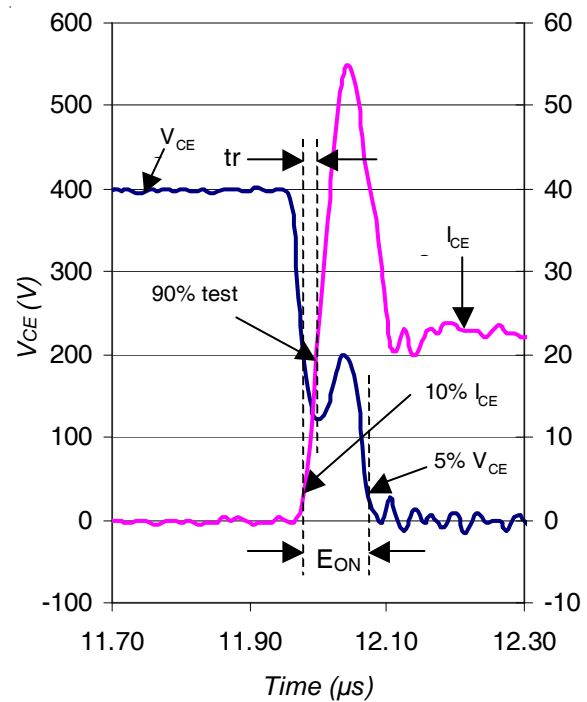


**Fig. 19** Maximum Transient Thermal Impedance, Junction-to-Case

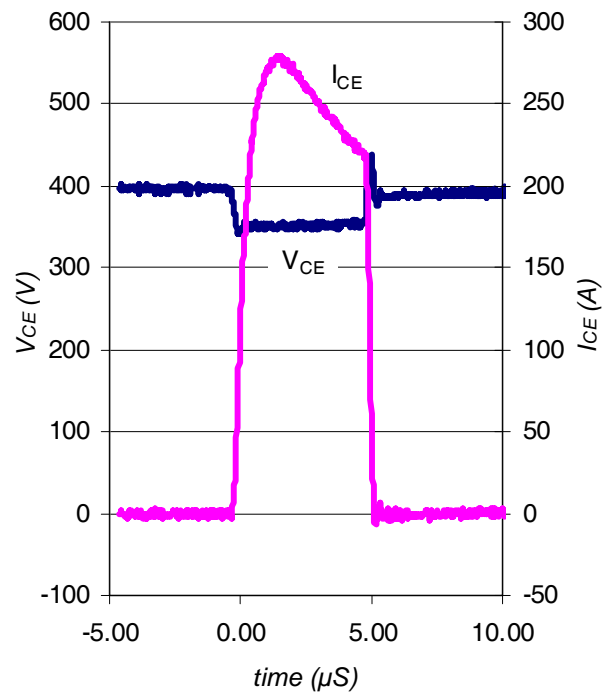

**Fig.C.T.1 - Gate Charge Circuit (turn-off)**

**Fig.C.T.2 - RBSOA Circuit**

**Fig.C.T.3 - S.C. SOA Circuit**

**Fig.C.T.4 - Switching Loss Circuit**

**Fig.C.T.5 - Resistive Load Circuit**

**Fig.C.T.6 - BVCES Filter Circuit**



**Fig. WF1** - Typ. Turn-off Loss Waveform  
@  $T_J = 175^\circ\text{C}$  using Fig. CT.4



**Fig. WF2** - Typ. Turn-on Loss Waveform  
@  $T_J = 175^\circ\text{C}$  using Fig. CT.4

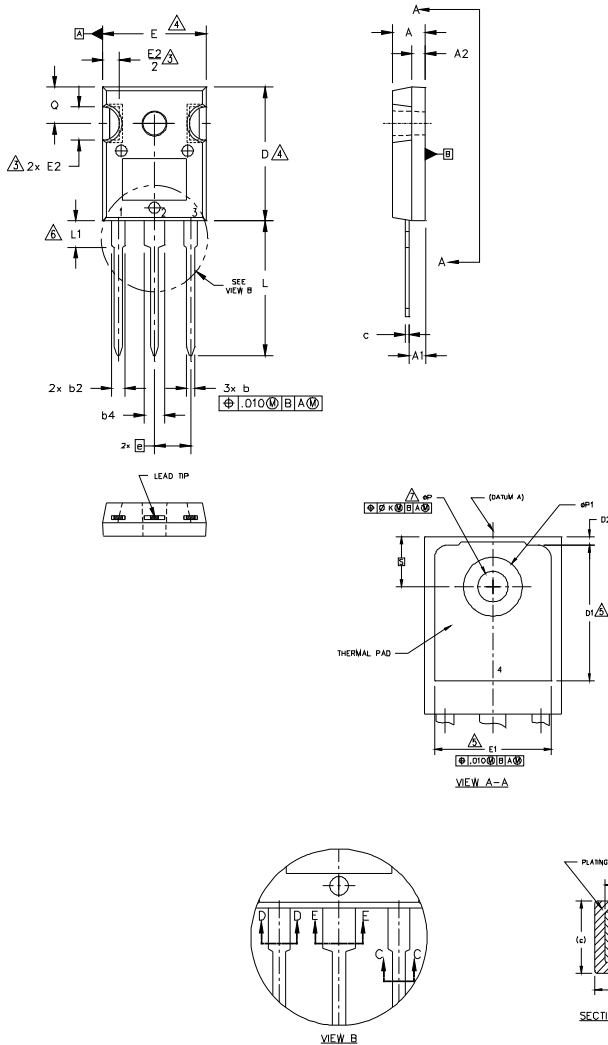


**Fig. WF3** - Typ. S.C. Waveform  
@  $T_J = 25^\circ\text{C}$  using Fig. CT.3



# TO-247AD Package Outline

Dimensions are shown in millimeters (inches)



**NOTES:**

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M 1994.
2. DIMENSIONS ARE SHOWN IN INCHES.
3. CONTOUR OF SLOT OPTIONAL.
4. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS D1 & E1.
6. LEAD FINISH UNCONTROLLED IN L1.
7. ØP TO HAVE A MAXIMUM DRAFT ANGLE OF 1.5 ° TO THE TOP OF THE PART WITH A MAXIMUM HOLE DIAMETER OF .154 INCH.
8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-247AD.

SYMBOL	DIMENSIONS				NOTES
	INCHES		MILLIMETERS		
	MIN.	MAX.	MIN.	MAX.	
A	.183	.209	4.65	5.31	
A1	.087	.102	2.21	2.59	
A2	.059	.098	1.50	2.49	
b	.039	.055	0.99	1.40	
b1	.039	.053	0.99	1.35	
b2	.065	.094	1.65	2.39	
b3	.065	.092	1.65	2.34	
b4	.102	.135	2.69	3.43	
b5	.102	.133	2.59	3.38	
c	.015	.035	0.38	0.89	
c1	.015	.033	0.38	0.84	
D	.776	.815	19.71	20.70	4
D1	.515	-	13.08	-	5
D2	.020	.053	0.51	1.35	
E	.602	.625	15.29	15.87	4
E1	.530	-	13.46	-	
E2	.178	.216	4.52	5.49	
e	.215 BSC		5.46 BSC		
Øk	.010		0.25		
L	.780	.827	19.57	21.00	
L1	.146	.169	3.71	4.29	
L	.140	.144	3.56	3.66	
ØP1	-	.291	-	7.39	
Q	.209	.224	5.31	5.69	
S	.217 BSC		5.51 BSC		

**LEAD ASSIGNMENTS**

**HEXFET**

- 1.- GATE
- 2.- DRAIN
- 3.- SOURCE
- 4.- DRAIN

**IGBTs, CoPACK**

- 1.- GATE
- 2.- COLLECTOR
- 3.- EMITTER
- 4.- COLLECTOR

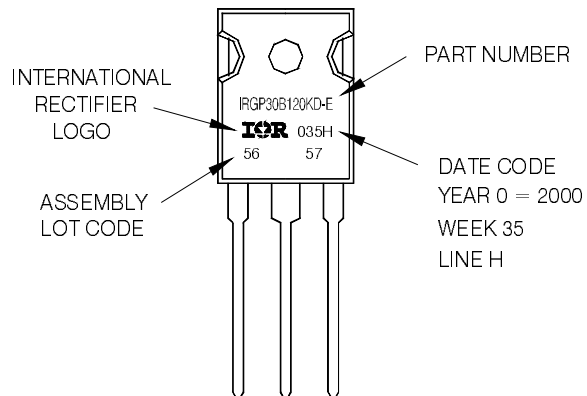
**DIODES**

- 1.- ANODE / OPEN
- 2.- CATHODE
- 3.- ANODE

## TO-247AD Part Marking Information

EXAMPLE: THIS IS AN IRGP30B120KD-E  
WITH ASSEMBLY  
LOT CODE 5657  
ASSEMBLED ON WW 35, 2000  
IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line position  
indicates "Lead-Free"



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

**Qualification Information†**

<b>Qualification Level</b>		Industrial (per International Rectifier's internal guidelines)	
<b>Moisture Sensitivity Level</b>		TO-247AD	N/A (per JEDEC J-STD-020D)
<b>ESD</b>	Machine Model	Class M4 (+/- 700V ) (per AEC-Q101-002)	
	Human Body Model	Class H1C (+/- 2000V ) (per AEC-Q101-001)	
	Charged Device Model	Class C5(+/- 2000V ) (per AEC-Q101-005)	
<b>RoHS Compliant</b>		Yes	

† Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/product-info/reliability>

Data and specifications subject to change without notice.

International  
 Rectifier

**IR WORLD HEADQUARTERS:** 101 N. Sepulveda Blvd., El Segundo, California 90245, USA Tel: (310) 252-7105  
 TAC Fax: (310) 252-7903

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